

## In the Claims

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 C.F.R. § 1.121(c)(1)(i). Cancel all previous versions of any pending claim.

A marked up version showing amendments to any claims being changed is provided in one or more accompanying pages separate from this amendment in accordance with 37 C.F.R. § 1.121(c)(1)(ii). Any claim not accompanied by a marked up version has not been changed relative to the immediate prior version, except that marked up versions are not being supplied for any added claim or canceled claim.

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1. (Amended) A method of preparing a liquid for a semiconductor fabrication polishing process comprising:  
providing a liquid;  
degassifying the liquid; and  
injecting a gas into the liquid to regassify the liquid, the regassification increasing a total dissolved gas concentration in the liquid to greater than or equal to 200 ppb, the liquid having the increased total dissolved gas concentration for use in the polishing process.

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3. The method of claim 1 wherein the providing, provides a water comprising liquid for the semiconductor polishing process.

4. The method of claim 1 wherein the semiconductor polishing process comprises an etch process.